

Data sheet acquired from Harris Semiconductor SCHS065C – Revised November 2004

CMOS Dual Monostable Multivibrator

High-Voltage Types (20-Volt Rating)

CD4098B dual monostable multivibrator provides stable retriggerable/resettable one-shot operation for any fixed-voltage timing application.

An external resistor $(R\chi)$ and an external capacitor (C_X) control the timing for the circuit. Adjustment of R_X and C_X provides a wide range of output pulse widths from the Q and \overline{Q} terminals. The time delay from trigger input to output transition (trigger propagation delay) and the time delay from reset input to output transition (reset propagation delay) are independent of Rx and CX.

Leading-edge-triggering (+TR) and trailing-edge-triggering (-TR) inputs are provided for triggering from either edge of an input pulse. An unused +TR input should be tied to VSS. An unused -TR input should be tied to VDD. A RESET (on low level) is provided for immediate termination of the output pulse or to prevent output pulses when power is turned on. An unused RESET input should be tied to VDD. However, if an entire section of the CD4098B is not used, its RESET should be tied to VSS. See Table I.

In normal operation the circuit triggers (extends the output pulse one period) on the application of each new trigger pulse. For operation in the non-retriggerable mode, $\overline{\mathbf{Q}}$ is connected to -TR when leading-edge triggering (+TR) is used or Q is connected to +TR when trailing-edge triggering (-TR) is used.

The time period (T) for this multivibrator can be approximated by: $T_X = \frac{1}{2}R_X C_X$ for $C_X \ge$ 0.01 µF. Time periods as a function of Rx for values of C_X and V_{DD} are given in Fig. 8. Values of T vary from unit to unit and as a function of voltage, temperature, and RXCX.

The minimum value of external resistance, R_X , is 5 k Ω . The maximum value of external capacitance, C χ , is 100 μ F. Fig. 9 shows time periods as a function of C_X for values of R_X and VDD.

The output pulse width has variations of $\pm 2.5\%$ typically, over the temperature range of $-55^{\circ}C$ to $125^{\circ}C$ for $C\chi$ =1000 pF and $R_X = 100 k\Omega$.

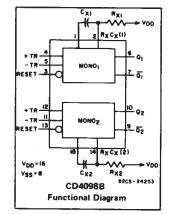
For power supply variations of ±5%, the output pulse width has variations of $\pm 0.5\%$ typically, for VDD=10 V and 15 V and ±1% typically, for VDD=5 V at Cx=1000 pF and Rχ=5 kΩ.

These types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix). 16-lead small-outline packages (M, M96, and MT suffixes), and 16-lead thin shrink smalloutline packages (PW and PWR suffixes).

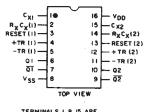
The CD4098B is similar to type MC14528.

Features:

- Retriggerable/resettable capability
- Trigger and reset propagation delays independent of R_X , C_X
- Triggering from leading or trailing edge
- Q and Q buffered outputs available
- Separate resets
- Wide range of output-pulse widths
- 100% tested for maximum quiescent current at 20 V
- Maximum input current of 1 μ A at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (full package-temperature range): 1 V at V_{DD}= 5 V
- 2 V at VDD=10 V 2.5 V at VDD=15 V 5.7, 10-V, and 15-V parametric ratings Standardized, symmetrical output characteristics
- Meets all requirements of JEDEC Tentative Standard No. 13B,"Standard Specifications for Description of 'B' Series CMOS Devices."
- Applications:
- Pulse delay and timing
- Pulse shaping
- Astable multivibrator



CD4098B Types



TERMINALS 1,8,15 ARE ELECTRICALLY CONNECTED INTERNALLY 92CS-2484881

TERMINAL ASSIGNMENT

MAXIMUM RATINGS, Absolute-Maximum Values:	
DC SUPPLY-VOLTAGE RANGE, (VDD)	
Voltages referenced to V _{SS} Terminal)	
INPUT VOLTAGE RANGE, ALL INPUTS	
DC INPUT CURRENT, ANY ONE INPUT	
POWER DISSIPATION PER PACKAGE (PD):	
For $T_A = -55^{\circ}C$ to $+100^{\circ}C$	
For T _A = +100°C to +125°C Derate Linearity at 12mW/°C to 200mW	
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR T _A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	
OPERATING-TEMPERATURE RANGE (T _A)	
STORAGE TEMPERATURE RANGE (Tstg)65°C to +150°C	
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max +265°C	

CHARACTERISTIC	VDD	LIM	UNITS	
CHARACTERISTIC	V	MIN MAX		
Supply-Voltage Range (For T _A = Full Package-Temperature Range)	-	3	18	v,
Trigger Pulse Width t _W (TR)	5 10 15	140 60 40	-	กร
Reset Pulse Width $t_W(R)$ (This is a function of C_X)		See Dynamic Char. Chart and Fig. 10		·
Trigger Rise or Fall Time t _r (TR), t _f (TR)	5 - 15	-	100	μs

RECOMMENDED OPERATING CONDITIONS

			TABLE	ĒI					AMBIENT TEMPERATURE (TA)- 25 °C-									
CD	4098B FL	INCTION	AL TER	MINAL	ONNEC	TIONS												
FUNCTION	V _{DD} TO TERM. NO.					V _{SS} TO TERM. NO.				INPUT PULSE TO TERM. NO.				OTHER CONNECTIONS		E OTHER D. CONNECTIONS		
	MONO	MONO2	MONO1	MONO2	MONO	MONO2	MONO	MONO2										
Leading-Edge Trigger/ Retriggerable	3, 5	11, 13			4	_12												
Leading-Edge Trigger/ Non-retriggerable	3	13		· · ·	4	12	5-7	11.9	5 DRAIN-TO-SOURCE VOLTAGE (VDS)- Fig. 1 - Typical output low									
Trailing-Edge Trigger/ Retriggerable	3	13	4	12	5	11		· · · · · · · · · · · · · · · · · · ·	AMBIENT TEMPERATURE (T _A)-25*C									
Trailing-Edge Trigger/ Non-retriggerable	3	13			5	11	4-6	12.10										
Unused Section	5	11	3, 4	12, 13														

1. A RETRIGGERABLE ONE-SHOT MULTI-VIBRATOR HAS AN OUTPUT PULSE WIDTH WHICH IS EXTENDED ONE FULL TIME PERIOD (TX) AFTER APPLICATION OF THE LAST TRIGGER PULSE. The minimum time between retriggering edges (or trigger and retrigger edges) is 40 per cent of (T_X) .

MULTIVIBRATOR HAS A TIME PERIOD T_X REFERENCED FROM THE APPLI-CATION OF THE FIRST TRIGGER PULSE.

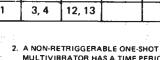
INPUT PULSE TRAIN

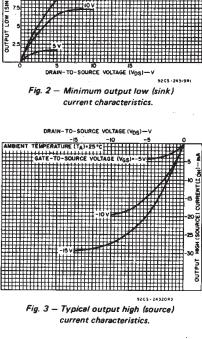
RETRIGGERABLE MODE PULSE WIDTH (+TR MODE)

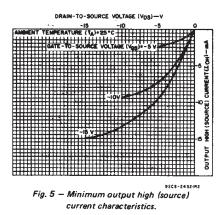
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NON-RETRIGGERABLE MODE PULSE WIDTH (+TR MODE)

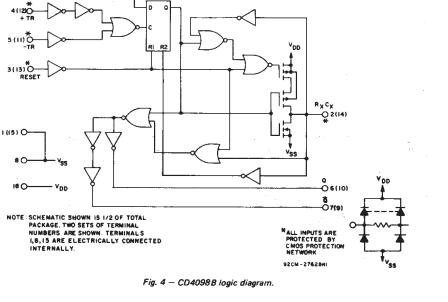






3 COMMERCIAL CMOS HIGH VOLTAGE ICS

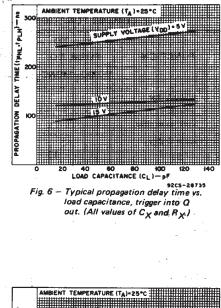
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STATIC ELECTRICAL CHARACTERISTICS

CHARAC- TERISTIC	CONDITIONS									PC)	UNITS	
	Vo	· V _{IN}	V _{DD}						+25	2.04723.4	ં અને	
·	(V)	(V)	-(V)	55	_40	+85	+125	Min.	Typ.	Max.		
Quiescent		0,5	5.1	1	1	30	30	-	0.02	1		
Device		0,10	10	2	2	60	60	- 1	0.02	2	1.	
Current		0,15	15	4	4	120	120	- 1	0.02	4	μΑ	
IDD Max.	-	0,20	20	20	20	600	600	-	0.04	20		
Output Low						:		<u> </u>				
(Sink)	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	_		
Current,	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	-		
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8		(_ +	
Output High	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	† <u>-1</u>		mA	
(Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	1	
Current,	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6			
IOH Min.	13.5	0,15	15	-4.2	_4	-2.8	-2.4	-3.4	-6.8	-		
Output Volt-				:			L	1		11		
age :		0,5	5		0.0)5		 _	0	0.05		
Low-Level,	-	0,10	10		0.0)5			0	0.05	n	
VOL Max.	-	0,15	15	Γ.	0.0)5		-	0	0.05		
Output Volt-								<u> </u>	i		V	
age:	_ ·	0,5	5		4.9	5		4.95	5	· -	·	
High-Level,	_	0,10	10		9.9			9.95	10	-		
V _{OH} Min.	_	0,15	15		14.	95		14.95	15			
Input Low	0.5,4.5	_	5		1.1	5				1.5		
Voltage,	1,9		10		3				_	3		
V _{IL} Max.	1.5,13.5	-	15		4				-	4		
Input High	0.5,4.5		- 5	3.5 3					_		V	
Voltage,	1,9	-	10	7 7								
V _{IH} Min.	1.5,13.5	e =	15							_		
Input Current, I _{IN} Max.	-	0,18	18	±0.1	±0.1	±1	±1	_	±10 ⁻⁵	±0.1	μA	



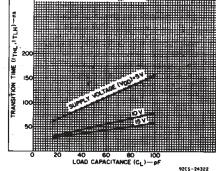


Fig. 7 – Transition time vs. load capacitance for $R_X = 5 k\Omega \cdot 10000 k\Omega$ and $C_X = 15 pF \cdot 10000 pF$.

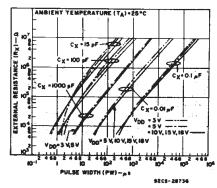


Fig. 8 – Typical external resistance vs. pulse width.

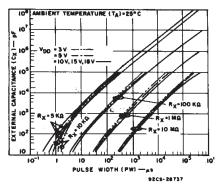


Fig. 9 – Typical external capacitance vs. pulse width.

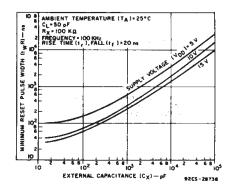


Fig. 10 – Typical minimum reset pulse width vs. external capacitance.

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DYNAMIC ELECTRICAL CHARACTERISTICS

At $T_A = 25^{\circ}C$; Input $t_r, t_f = 20 \text{ ns}$, $C_L = 50 \text{ pF}$, $R_L = 200 \text{ k}\Omega$

	TEST	CONDITI	LIM	LIANTO			
CHARACTERISTIC	$R_X(k\Omega)$	C _X (pF)	VDD (V)	Тур.	Max.	UNITS	
Trigger Propagation Delay Time	5 to		5	250	500		
+TR, –TR to Q, Q	10,000	≥15	10	125	250	ns	
tPHL, tPLH	10,000		15	100	200	1	
Minimum Trigger Pulse Width,	5 to		5	70	140		
•	10,000	≥15	10	30	60	ns	
^t WH ^{, t} WL	10,000		15	20	40		
Transition Time,	5 to		- 5	100	200		
^t TLH	10,000	≥15	10	50	100		
	10,000		15	40	80		
· · · ·	5 to	15 to	5	100	200		
	10,000	10,000	10	50	100		
			15	40	80		
	5 to	0.01 μF	5	150	300	ns	
^t THL	10,000	to	10	75	150		
		0.1 μF	15	65	130		
	5 to 10,000	0.1 μF	5	250	500		
		to	10 150	300			
		1μF	15	80	160		
Reset Propagation Delay Time,	5 to		5	225	450	1	
Трнц, Трцн	10,000	≥15	10	125	250	ns	
			15	75	150		
		15	5	100	200	ns	
			10	40	80		
			15	30	60		
Minimum Reset Pulse Width,			5	600	1200		
t _W R	100	1000	10	300	600		
**			15	250	500		
			5	25	50		
		0.1 μF	10	15	30	μs	
			15	10	20		
Trigger Rise or Fall Time	_	_	5 to	_	100	110	
t _r (TR), t _f (TR)		weet a final	15		2.14	μs	
Pulse Width Match		'n	5	5	10		
Between Circuits in	10	10,000	10	7.5	· 15	. %	
Same Package			15	7.5	15		
Input Capacitance, CIN		Any Input		5	7.5	рF	



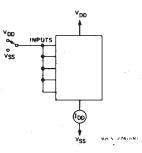


Fig. 12 – Quiescent-device-current test circuits.

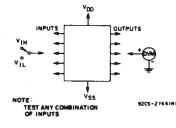


Fig. 13 - Input-voltage test circuit.

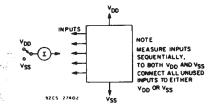


Fig. 14 — Input leakage current test circuit.

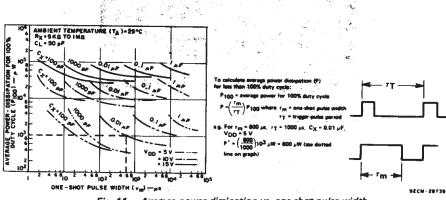
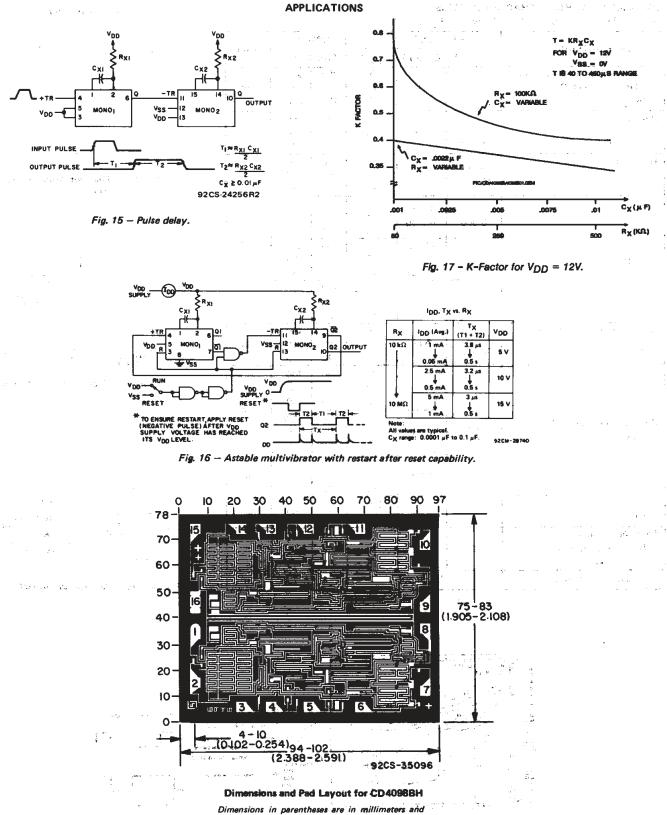


Fig. 11 — Average power dissipation vs. one-shot pulse width.

CD4098B Types



are derived from the basic inch dimensions as indicated. Grid graduations are in mils (†9⁻⁺³ inch).

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD4098BE	ACTIVE	PDIP	Ν	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CD4098BF	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4098BF3A	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4098BFB	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC
CD4098BM	ACTIVE	SOIC	D	16	40	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEA Level-1-235C-UNLIM
CD4098BM96	ACTIVE	SOIC	D	16	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEA Level-1-235C-UNLIM
CD4098BMT	ACTIVE	SOIC	D	16	250	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEA Level-1-235C-UNLIM
CD4098BPW	ACTIVE	TSSOP	PW	16	90	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
CD4098BPWR	ACTIVE	TSSOP	PW	16	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
JM38510/17504BEA	ACTIVE	CDIP	J	16	1	None	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



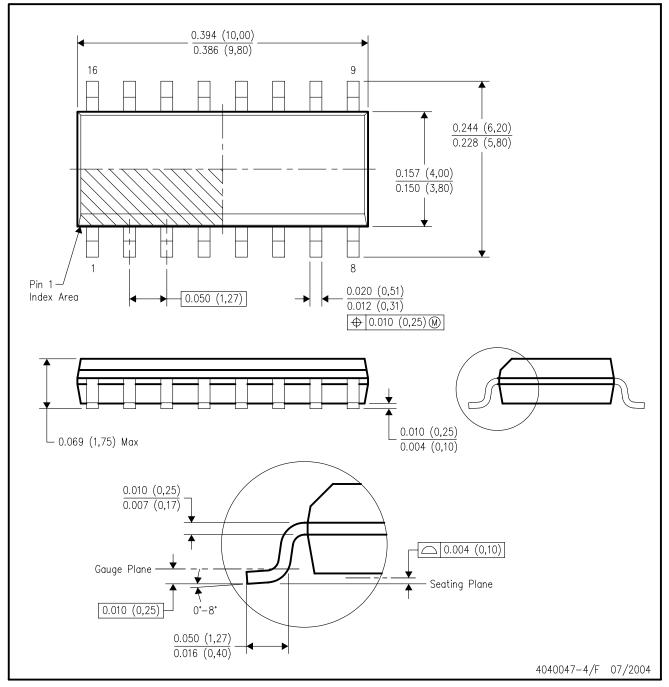
NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AC.



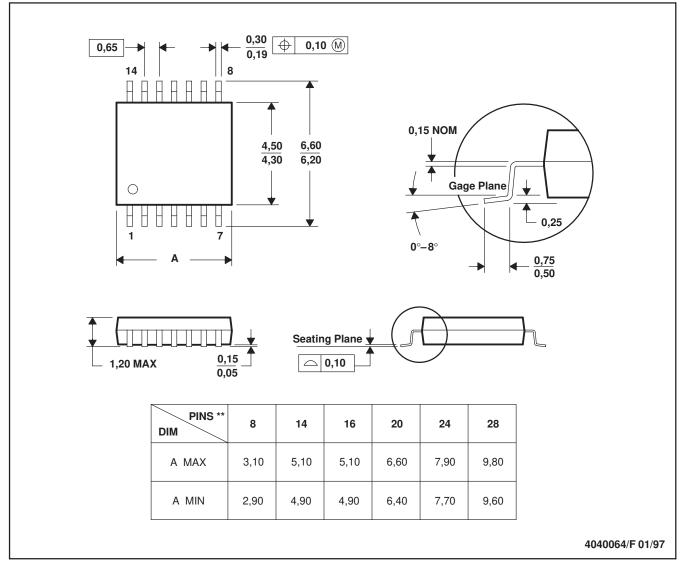
MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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